

**REMARKS**

Examiner T. Nguyen is thanked for the thorough examination and search of the subject Patent Application. Claim 23 has been amended and claim 25 has been canceled. No new matter has been added.

All Claims are believed to be in condition for Allowance, and that is so requested.

Reconsideration of the rejection under 35 U.S.C. 103(a) of Claims 23-25 and 27 as being unpatentable over Yang et al in view of You et al is requested in view of Amended Claim 23 and in accordance with the following remarks.

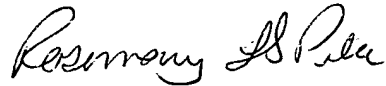
Claim 23 has been amended to include the adhesion promoter and stabilizer materials of SiC, BC, BN, and BCN from canceled claim 25. Yang et al does not teach or suggest the use of these materials over the low dielectric constant material (col. 6, lines 55-65). While it is agreed that You et al teaches curing of an HSQ low dielectric constant material, HSQ is not taught or suggested as the low dielectric constant material in either of Yang et al or Applicants' invention.

Reconsideration of the rejection under 35 U.S.C. 103(a) of Claims 23-25 and 27 as being unpatentable over Yang et al in view of You et al is requested in view of Amended Claim 23 and in accordance with remarks above.

Allowance of all Claims is requested.

It is requested that should Examiner Nguyen not find that the Claims are now Allowable that the Examiner call the undersigned at 765 4530866 to overcome any problems preventing allowance.

Respectfully submitted,

A handwritten signature in cursive script, appearing to read "Rosemary L. S. Pike".

Rosemary L. S. Pike. Reg # 39,332